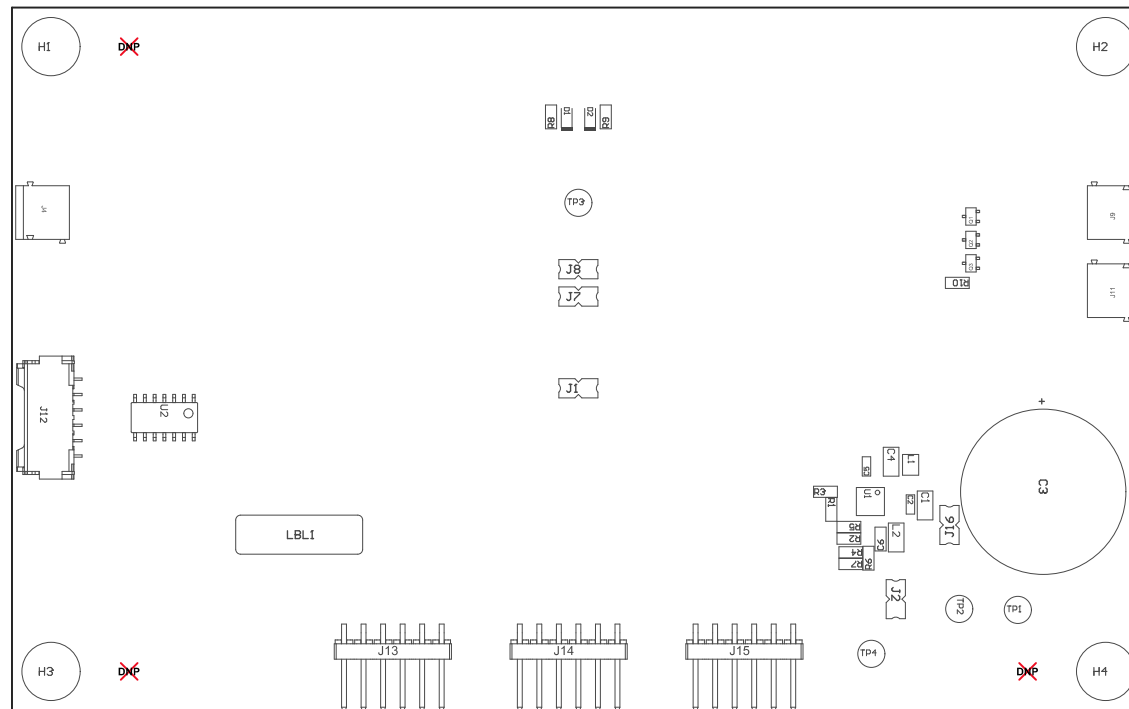
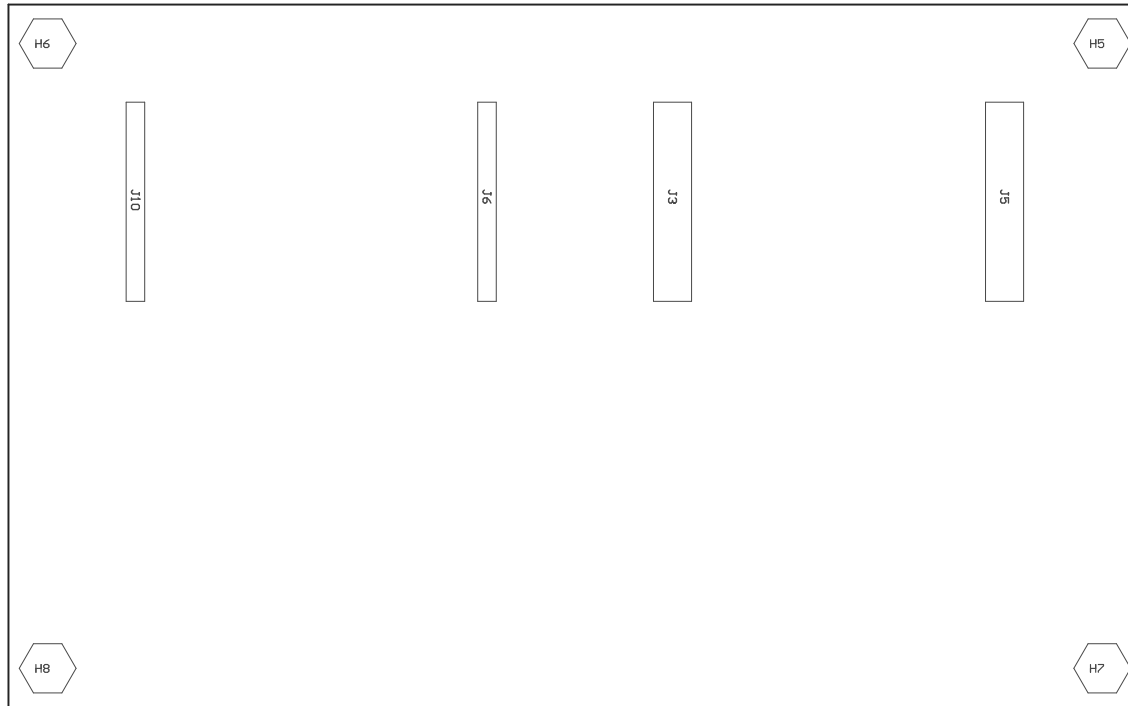


ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
 ZZ2 ■ This Assembly Note will show in the PcbDoc and associated outputs
 ZZ3 ■ This Assembly Note will show in the PcbDoc and associated outputs
 ZZ4 ■ This Assembly Note will show in the PcbDoc and associated outputs



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01528	REV: E1	SUN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Top Assembly Drawing	GENERATED : 10/18/2017 8:11:57 AM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

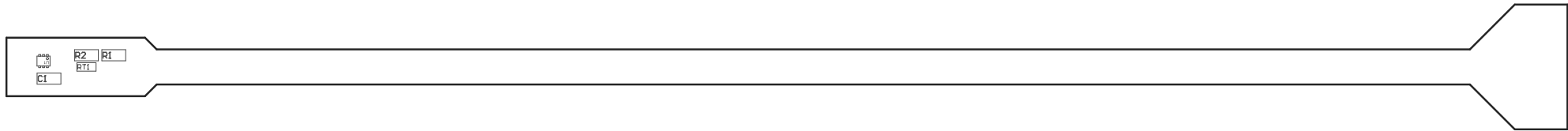
PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01528	REV: E1	SUN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 10/18/2017 8:11:58 AM		TEXAS INSTRUMENTS

ZZ1 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

ZZ2 ■ This Assembly Note will show in the PcbDoc and associated outputs

ZZ3 ■ This Assembly Note will show in the PcbDoc and associated outputs

ZZ4 ■ This Assembly Note will show in the PcbDoc and associated outputs



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01528	REV: E1	SVN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Top Assembly Drawing	GENERATED : 10/18/2017 8:12:32 AM	TEXAS INSTRUMENTS	

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01528	REV: E1	SUN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 10/18/2017 8:12:34 AM	TEXAS INSTRUMENTS	

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